



G00002

**RADIATION-CURABLE HEAT-PEELABLE PRESSURE-SENSITIVE
ADHESIVE SHEET AND PROCESS FOR PRODUCING CUT PIECES WITH
THE SAME**

ABSTRACT OF THE DISCLOSURE

A radiation-curable heat-peelable pressure-sensitive adhesive sheet is disclosed which has tackiness enabling adherends to withstand transportation and other steps, with which cutting can be conducted without flinging up an adhesive waste or causing chipping, and from which the cut pieces can be easily separated and recovered. The radiation-curable heat-peelable pressure-sensitive adhesive sheet comprises a substrate and, formed on at least one side thereof, a pressure-sensitive adhesive layer containing heat-expandable microspheres and a radiation-curable compound. A work to be cut is placed on the surface of the pressure-sensitive adhesive layer of the radiation-curable heat-peelable pressure-sensitive adhesive sheet, and the pressure-sensitive adhesive layer is irradiated with a radiation to cure the adhesive layer. The work is cut into pieces and the pressure-sensitive adhesive layer is then thermally foamed, before the cut pieces are separated and recovered from the adhesive sheet. Thus, cut pieces can be efficiently produced without arousing troubles in processing steps.

Figure 1



162162